Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-2. (Canceled)

3. (Previously Presented) The manufacturing process of conductive composition as in claim 11, wherein said first slurry and said second slurry have substantially the same composition.

4. (Canceled)

5. (Previously Presented) The manufacturing process of conductive composition as in claim 11, wherein an average particle size of said ceramics particles is less than that of said metal particles.

6. (Canceled)

7. (Previously Presented) The manufacturing process of conductive composition as in claim 11, wherein an average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

8-10. (Canceled)

11. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry,

wherein an average particle size of said metal particles is 0.5μm or ~~less.~~ less, and

an average particle size of said ceramics particles is a quarter of or less than the average particle size of said metal particles.

12. (Canceled)

13. (Previously Presented) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry,

wherein an average particle size of said ceramics particles is less than that of said metal particles, and

wherein an average particle size of said metal particles is 0.5μm or less.

14. (Canceled)

15. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry,

wherein said metal particles are Ni or Ni content ~~compound.~~ compound, and

an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

16. (Canceled)

17. (Previously Presented) The manufacturing process of conductive composition as in claim 11, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

18-21. (Canceled)

22. (Previously Presented) The manufacturing process of conductive composition as in claim 13, wherein said first slurry and said second slurry have substantially the same composition.

23. (Previously Presented) The manufacturing process of conductive composition as in claim 13, wherein an average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

24. (Previously Presented) The manufacturing process of conductive composition as in claim 13, wherein an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

25. (Previously Presented) The manufacturing process of conductive composition as in claim 13, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

26. (Previously Presented) The manufacturing process of conductive composition as in claim 15, wherein said first slurry and said second slurry have substantially the same composition.

27. (Previously Presented) The manufacturing process of conductive composition as in claim 15, wherein an average particle size of said ceramics particles is less than that of said metal particles.

28. (Previously Presented) The manufacturing process of conductive composition as in claim 15, wherein an average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

29. (Canceled)

30. (Previously Presented) The manufacturing process of conductive composition as in claim 15, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

31. (New) The manufacturing process of conductive composition as in claim 11, wherein a liquid for wetting said metal particles is a solvent being compatible with an organic component included in said conductive composition and incompatible with water.

32. (New) The manufacturing process of conductive composition as in claim 15, wherein a liquid for wetting said metal particles is a solvent being compatible with an organic component included in said conductive composition and incompatible with water.

33. (New) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed, and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along relatively different direction from the first slurry,

wherein an average particle size of said metal particles is 0.5 μm or less; and

a liquid for wetting said metal particles is a solvent being compatible with an organic component included in said conductive composition and incompatible with water.

34. (New) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed, and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along relatively different direction from the first slurry,

wherein said metal particles are Ni or Ni content compound; and

a liquid for wetting said metal particles is a solvent being compatible with an organic component included in said conductive composition and incompatible with water.